

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	6916	(semiconductor or die or chip or IC) and heat with (recess or cavity)	USPA T	2003/11/22 17:40
2	BRS	1037	L1 and heat adj sink with (recess or cavity)	USPA T	2003/11/22 18:56
3	BRS	284	(257/712 or 257/713 or 257/720) and heat adj sink with (recess or cavity)	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_ TDB	2003/11/22 18:59
4	BRS	252	(257/675 or 257/704 or 257/706) and heat adj sink with (recess or cavity)	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_ TDB	2003/11/22 19:08
5	BRS	253	(257/707 or 257/778 or 438/122) and heat adj sink with (recess or cavity)	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_ TDB	2003/11/22 19:09